

AMENDMENTS TO THE SPECIFICATION:

Please amend this application on page 1, line 1, by inserting the following new paragraph:

This is a divisional application of U.S. Patent Application Serial No. 10/396,407, filed March 26, 2003, which is a divisional application of U.S. Patent Application Serial No. 09/784,200, filed February 16, 2001 (now U.S. Patent No. 6,579,382 B2 issued June 17, 2003), all of which are incorporated herein by reference.

AMENDMENTS TO THE SPECIFICATION:

Replace the paragraph beginning on page 5, line 23, with the following paragraph:

Further, the second feature of the chemical liquid processing apparatus and chemical liquid processing method according to the present invention is that, a process for removing liquid supplied beforehand to a substrate comprising the steps of: holding said substrate; rotating a plate having an air intake hole [on] above said substrate; generating a negative pressure between the plate and a processing object substrate by rotating said plate; and generating air flow between said processing object substrate and said plate by sucking air through said air intake hole in the presence of the negative pressure.

Replace the paragraph beginning on page 15, line 29, and ending on page 16, line 8, with the following paragraph:

(3) Next, as shown in FIG. 10A, air flow is formed above the film of the chemical liquid 16 on the processing object substrate 10 by rotating a circular plate 28 disposed above the processing object substrate 10. The circular plate 28 is a larger disc than the processing object substrate 10 and disposed near the processing object substrate 10 such that it is not in contact with the surface of the chemical liquid film 16. The central portion of the circular plate 28 is hollow and this section can be opened or

closed by a valve (not shown). It is effective to rotate the processing object substrate 10 when the air flow is [formed] generated by a rotation of the substrate holding portion [11] 12. In this case, the rotation direction of the processing object substrate 10 is desired to coincide with the direction of air flow (S103).

Replace the paragraph beginning on page 20, line 35, and ending on page 21, line 12, with the following paragraph:

As shown in Fig. 14, the substrate drying apparatus of the embodiment of the present invention comprises: a substrate holding portion 102 for holding a processing object substrate 101 on its top face; a plate 103 disposed above the substrate holding portion 102 and made of a flat circular plate of 320 mm in diameter including an air intake hole [12a] 103a of 32 mm in diameter in the center thereof; and an air flow control wall 104 provided so as to surround the substrate holding portion 102 for preventing the substrate holding portion 102 from sucking air. Further, according to this embodiment, the substrate holding portion 102, the plate 103 and the air flow control wall 104 are covered with an outer cover 105.

Replace the paragraph beginning on page 35, line 22, with the following paragraph:

Further, in the chemical liquid processing method according to the second embodiment of the present invention, it is desirable to [form] generate [air] a gas flow in [de-carbonizing] a de-carbonized environment, which is an environment which does not contain carbon dioxide. Consequently, mixing of CO₂ into air flow can be prevented.